

GLOSSARY of Printed Circuit Design and Manufacturing

| No. | GLOSSARY | Meanings |
|-----|-------------------|--|
| 1 | TAB | Tape Automated Bonding |
| 2 | tented via | a via with dry film solder mask completely covering both its pad and its plated-thru hole. This completely insulates the via from foreign objects, thus protecting against accidental shorts, but it also renders the via unusable as a test point. Sometimes vias are tented on the top side of the board and left uncovered on the bottom side to permit probing from that side only with a test fixture. |
| 3 | TDR | Time Domain Reflectometer, a device which a board house can use for measuring characteristic impedance of a conductor on a printed board, thus insuring an accurate build for controlled impedance. |
| 4 | terminal | A point of connection for two or more conductors in an electrical circuit; one of the conductors is usually an electrical contact, lead or electrode of a component. |
| 5 | terminal block | a type of header to which wires are attached directly instead of by means of a connector plug. Each wire is inserted in a hole in the terminal block , and then anchored by means of a screw. |
| 6 | test coupon | An area of patterns and holes located on the same fabrication panel as the actual PCB, but separate from the electrical circuits and outside the board outline(s). It is designed to reflect the technology used on the PCB, such as smallest plated-through hole size, any blind or buried vias, etc. It is cut away from the panel and can be embedded in a clear plastic to prepare it for destructive testin |
| 7 | thin film | A film of conductive or insulating material, usually deposited by sputtering or evaporation, that may be made in a pattern to form electronic components and conductors on a substrate or used as insulation between successive layers of components |
| 8 | through-hole | (Of a component, also spelled "thru-hole"). Having pins designed to be inserted into holes and soldered to pads on a printed board. Contrast with surface mount . |
| 9 | thru-hole | Same as through-hole |
| 10 | TQFP | Thin Quad Flat Pack. Essentially the same as a QFP except low-profile, that is, thinner |
| 11 | trace | Segment of a route . |
| 12 | Trillium | A company that makes DUT or ATE systems |
| 13 | TTL | Transistor-Transistor Logic. Also called multiple-emitter transistor logic. A widely used form of semiconductor logic. Its basic logic element is a multiple-emitter transistor. TTL is characterized by fairly high speed and medium power dissipation |
| 14 | UL | Underwriter's Laboratories, Inc., a corporation supported by some underwriters for the purpose of establishing safety standards on types of equipment or components. |
| 15 | unsaturated logic | A form of logic containing transistors operated outside the region of saturation , which makes for very fast switching. An example is emitter-coupled logic (ECL). |
| 16 | US-ASCII | The 7-bit (using character codes 0-127) version of ASCII , which preceded (and is the basis for) 8-bit versions such as Latin-1, MacASCII and later, even larger coded character sets such as Unicode. |